Last Updated: Oct. 2005

NAND Flash PART NUMBERING

HY XX X X XX XX X X - X (X) (X) (X) (X)

(1) (2) (3) (4) (5) (6) (7) (8) (9) (10) (11) (12) (13)

(1) HYNIX MEMORY

(2) COMPONENT GROUP

27 : NAND Flash

(3) POWER SUPPLY(Vcc)

U : 2.7V~3.6V
L : 2.7V
S : 1.8V

(4) CLASSIFICATION

S : SLC + Single Die + S/B
A : SLC + Double Die + S/B
B : SLC + Quadruple Die + S/B
F : SLC + Single Die + L/B
G : SLC + Double Die + L/B
H : SLC + Quadruple Die + L/B
T : MLC + Single Die + L/B
U : MLC + Double Die + L/B
V : MLC + Quadruple Die + L/B

(5) BIT ORGANIZATION

08 : x8
16 : x16
32 : x32

(6) DENSITY

64	: 64Mb	28	: 128Mb
56	: 256Mb	12	: 512Mb
1G	: 1Gb	2G	: 2Gb
4G	: 4Gb	8G	: 8Gb
AG	: 16Gb	BG	: 32Gb
CG	: 64Gb	DG	: 128Gb

(7) MODE

1 : 1 nCE & 1 R/nB; Sequential Row Read Enable
2 : 1 nCE & 1 R/nB; Sequential Row Read Disable
4 : 2 nCE & 2 R/nB; Sequential Row Read Enable
5 : 2 nCE & 2 R/nB; Sequential Row Read Disable
6 : 1 nCE & 1 R/nB; Sequential Row Read Enable & Auto Read Page 0
7 : 2 nCE & 2 R/nB; Sequential Row Read Enable & Auto Read Page 0
8 : 1 nCE & 1 R/nB; Sequential Row Read Disable & Auto Read Page 0
9 : 2 nCE & 2 R/nB; Sequential Row Read Disable & Auto Read Page 0
D : Dual Interface; Sequential Row Read Disable

(8) VERSION

M : 1st Gen.
A : 2nd Gen.
B : 3rd Gen.
C : 4th Gen.
1 : Down Density(1st)
2 : Down Density(2nd)

(9) PACKAGE TYPE

T : TSOP1
V : WSOP
S : USOP
F : FBGA(63ball)
B : FBGA(107ball)
G : FBGA(149ball)
H : TBGA
L : LGA
U : ULGA
M : TLGA
W : Wafer
C : Chip
K : KGD

(10) PACKAGE MATERIAL

Blank : Normal, Wafer, Chip, KGD
P : Lead Free
H : Halogen Free
R : Lead & Halogen Free

(11) OPERATING TEMPERATURE

Blank : Wafer, Chip
C : 0℃~70℃
E : -25℃~85℃
M : -30℃~85℃
I : -40℃~85℃

(12) BAD BLOCK

Blank : Wafer
B : Included Bad Block
S : 1~5 Bad Block
P : All Good Block

(13) OPTION(CUSTOMER)

Customer Initial Option